



AZ 5214 E

Image Reversal
Photoresist

GENERAL INFORMATION

This special photoresist is intended for lift-off-techniques which call for a negative wall profile. Although they are positive photoresists (and may even be used in that way) comprised of a novolak resin and naphthoquinone diazide as photoactive compound (PAC) they are capable of image reversal (IR) resulting in a negative pattern of the mask. In fact AZ 5214E is almost exclusively used in the IR-mode.

The image reversal capability is obtained by a special crosslinking agent in the resist formulation which becomes active at temperatures above 110°C and - what is even more important - only in exposed areas of the resist. The crosslinking agent together with exposed PAC leads to an almost insoluble (in developer) and no longer light sensitive substance, while the unexposed areas still behave like a normal unexposed positive photoresist. After a flood exposure (no mask required) this areas are dissolved in standard developer for positive photoresist, the crosslinked areas remain. The overall result is a negative image of the mask pattern.

As everybody knows a positive photoresist profile has a positive slope of 75 - 85° depending on the process conditions and the performance of the exposure equipment (only submicron-resists get close to 90°). This is mainly due to the absorption of the PAC which attenuates the light when penetrating through the resist layer (so called bulk effect). The result is a higher dissolution rate at the top and a lower rate at the bottom of the resist. When AZ 5214E is processed in the IR-mode this is reversed as higher exposed areas will be crosslinked to a higher degree than those with lower dose, dissolution rates accordingly. The final result will be a negative wall profile ideally suited for lift-off.

The most critical parameter of the IR-process is reversal-bake temperature, once optimised it must be kept constant within $\pm 1^\circ\text{C}$ to maintain a consistent process. This temperature also has to be optimised individually. In any case it will fall within the range from 115 to 125°C. If IR-temperature is chosen too high ($>130^\circ\text{C}$) the resist will thermally crosslink also in the unexposed areas, giving no pattern. To find out the suitable temperature following procedure is suggested:

Coat and prebake a few substrates with resist. Without exposing them to UV-light subject them to different reversal-bake temperatures, i.e. 115°, 120°, 125° and 130°C. Now apply a flood exposure of $> 200\text{mJ}/\text{cm}^2$ and afterwards immerse them into a standard developer make up, i.e. AZ 351B, 1:4 diluted, or AZ 726 MIF for 1 minute. From a part of the substrates the resist will be removed, another part (those exposed to a too high temperature) will remain with the resist thermally crosslinked on it. Optimum RB-temperature now is 5° to 10°C below the temperature where crosslinking starts.

The flood exposure is absolutely uncritical as long as sufficient energy is applied to make the unexposed areas soluble. 200 mJ/cm^2 is a good choice, but 150 - 500 mJ/cm^2 will have no major influence on the performance.

Finally it should be noted that the imagewise exposure energy is lower than with normal positive processes, generally only half of that. So a good rule of thumb is: compared to a standard positive resist process, imagewise exposure dose should be half of that, flood exposure energy double of that for AZ 5214E IR-processing.

Once understanding and being familiar with this IR-procedure it is quite simple to set up a different process for lift-off. A T-shaped profile can be achieved by the following process sequence:

The prebaked AZ 5214E photoresist is flood exposed (no mask) with a small amount of UV energy, just to generate some exposed PAC at the surface. Now the reversal-bake is performed to partially crosslink this top areas. By this treatment a top layer with a lowered dissolution rate compared to the bulk material is generated. After this the resist is treated like a normal positive photoresist (imagewise exposure and development) to generate a positive image! Due to the lower dissolution rate in the top layer a T-shaped profile with overhanging lips will be the result.

PHYSICAL and CHEMICAL PROPERTIES

		AZ 5214E	
Solids content [%]		28.3	
Viscosity [cSt at 25°C]		24.0	
Absorptivity [l/g*cm] at 377nm		0.76	
Solvent	methoxy-propyl acetate (PGMEA)		
Max. water content [%]		0.50	
Spectral sensitivity		310 - 420 nm	
Coating characteristic		striation free	
Filtration [µm absolute]		0.1	

FILM THICKNESS [µm] as FUNCTION of SPIN SPEED (characteristically)

spin speed [rpm]	2000	3000	4000	5000	6000
AZ 5214E	1.98	1.62	1.40	1.25	1.14

PROCESSING GUIDELINES

Dilution and edge bead removal	AZ EBR Solvent
Prebake	110°C, 50", hotplate
Exposure	broadband and monochromatic h- and i-line
Reversal bake	120°C, 2 min., hotplate (most critical step)
Flood exposure	> 200 mJ/cm ² (uncritical)
Development	AZ 351B, 1:4 (tank, spray) or AZ 726 (puddle)
Postbake	120°C, 50s hotplate (optional)
Removal	AZ 100 Remover, conc.

HANDLING ADVISES

Consult the **Material Safety Data Sheets** provided by us or your local agent!

This AZ Photoresists are made up with our patented safer solvent PGMEA. They are **flammable liquids** and should be kept away from oxidants, sparks and open flames.

Protect from light and heat and store in sealed original containers between 0°C and 25°C, exceeding this range to -5°C or +30°C for 24 hours does not adversely affect the properties.

Shelf life is limited and depends on the resist series. The **expiration date** is printed on the label of every bottle below the batch number and coded as **[year/month/day]**.

AZ Photoresists are compatible with most commercially available wafer processing equipment. **Recommended materials** include PTFE, stainless steel and high-density poly-ethylene and -propylene.

The information contained herein is, to the best of our knowledge, true and accurate, but all recommendations are made without guarantee because the conditions of use are beyond our control. There is no implied warranty of merchantability or fitness for purpose of the product or products described here. In submitting this information, no liability is assumed or license or other rights expressed or implied given with respect to any existing or pending patent, patent application, or trademarks. The observance of all regulations and patents is the responsibility of the user.

AZ, the AZ logo, BARLi, Aquatar and Kallista are registered trademarks of Clariant AG.

Clariant GmbH
Business Unit
Electronic Materials
Rheingaustrasse 190
D-65203 Wiesbaden
Germany
Tel. +49 (611) 962-6867
Fax +49 (611) 962-9207

Clariant Corporation
Business Unit
Electronic Materials
70 Meister Avenue
Somerville, NJ 08876-1252
USA
Tel. +1 (908) 429-3500
Fax +1 (908) 429-3631

Clariant (Japan) K.K.
Business Unit
Electronic Materials
9F Bunkyo Green Court Center
2-28-8 Honkomagome Bunkyo-Ku
Tokyo 113, Japan
Tel. +81 (3) 5977-7973
Fax +81 (3) 5977-7894

Clariant Industries Ltd.
Business Unit
Electronic Materials
84-7, Chungdam-dong,
Kangnam-ku
Seoul Republic of Korea
Tel. +82 (2) 510-8000/8442
Fax +82 (2) 514-5918

